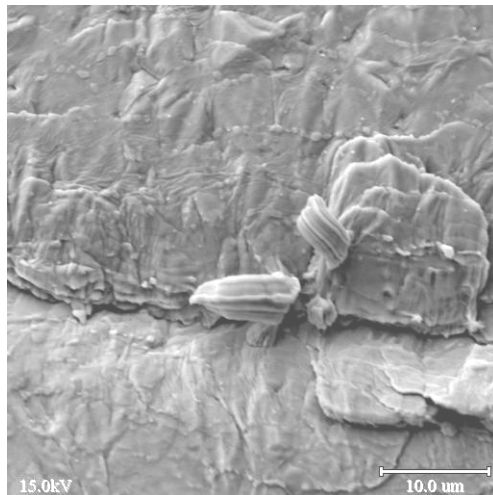


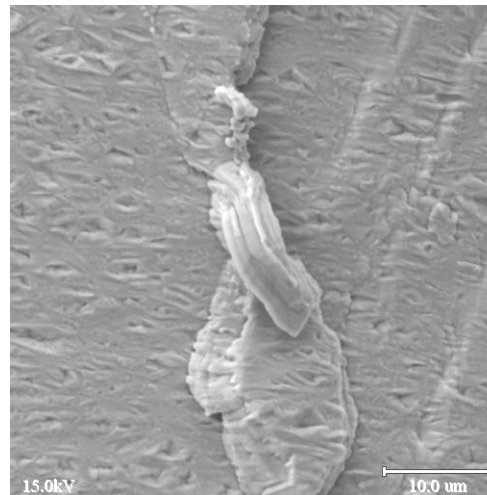
# Board-Level Whisker Testing

## (Sn/3.8Ag/0.7Cu Solder, 500 -55°C/85°C Temp Cycling)

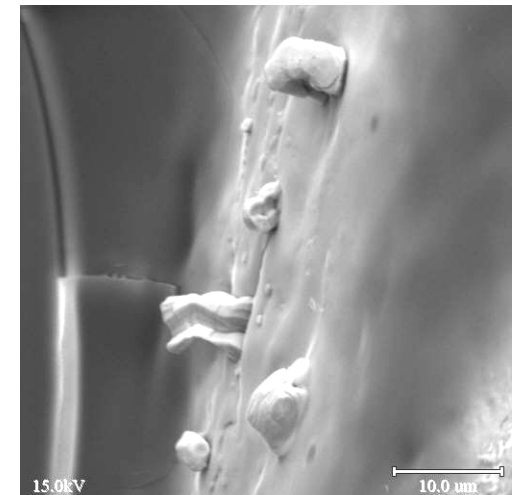
Package	Plating	Quantity	Max Length (μm)
64 LQFP	Sn	0-10	8
	Sn/2Bi	0-6	<b>15</b>
	Sn/15Pb	<b>75-177</b>	12



Whisker on top of shoulder- Sn finish



Whisker on top of foot - SnBi finish



Whisker on solder - SnPb finish

- Whiskers formed after surface mount, even on the solder
- Solder may also be prone to whisker growth

# Summary of Findings

- Sn/10-15Pb generally performed better than Sn and Sn/2-3Bi, which performed better than Sn/0.7Cu.
- Ni underplate did not retard whisker growth.
- External stress did not exacerbate whisker growth.
- Whiskers formed with 60°C/95%RH storage and -55°C/85°C temperature cycling.
- Whisker appears to form from surface grains, may be related to intermetallics formed between grain boundaries.
- Whiskers formed even after surface mount.
- Solder may also be prone to whisker growth.

# Future Work

- Continue evaluation of various supplier chemistries.
- Complete correlation studies, temp cycle to ambient .
- Perform additional FIB analysis with other finishes.
- Perform reflow study with whiskered terminals.
- Initiate whisker study with Pb-free solders.
- Continue to participate in NEMI studies and discussions to define a standard accelerated whisker test method along with failure criteria and correlation to ambient.